

ABSTRACT OF THE DISCLOSURE

A fabrication method of wafer level packages
5 capable of improving reliability by maximizing a contact area
of metal wiring and a conductive ball and of simplifying
fabrication processes by reducing the number of sputtering.
The disclosed method comprises the steps of: providing a
substrate having a plurality of chip pads on the upper part
10 thereof; forming a first insulating layer including a first
opening exposing the chip pad and a second opening forming a
ball land on the substrate; forming metal wiring connected to
the chip pad in a single unit through the first opening and
covering the second opening to have a ball land on the first
15 insulating layer; forming a second insulating layer including
a third opening which covers the metal wiring, however,
exposes the ball land; and adhering a conductive ball to be
in contact with the third opening on the ball land.